

Connector Datasheet

PT06J0000AY9

RJ45 1X1 Tab UP Only Left LED W/All Spring
W/10G Base-T Transformer

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TECHNICAL INFORMATION

1 SCOPE

1.1 Content

1.1.1 This specification covers performance, tests and quality requirements for RJ45 1X1 Tab UP Only Left LED W/All Spring W/2.5G Base-T Transformer.W/10G Base-T Transformer

2 APPLICABLE DOCUMENTS

The following documents form a part of this specification to the extent specified herein.

Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

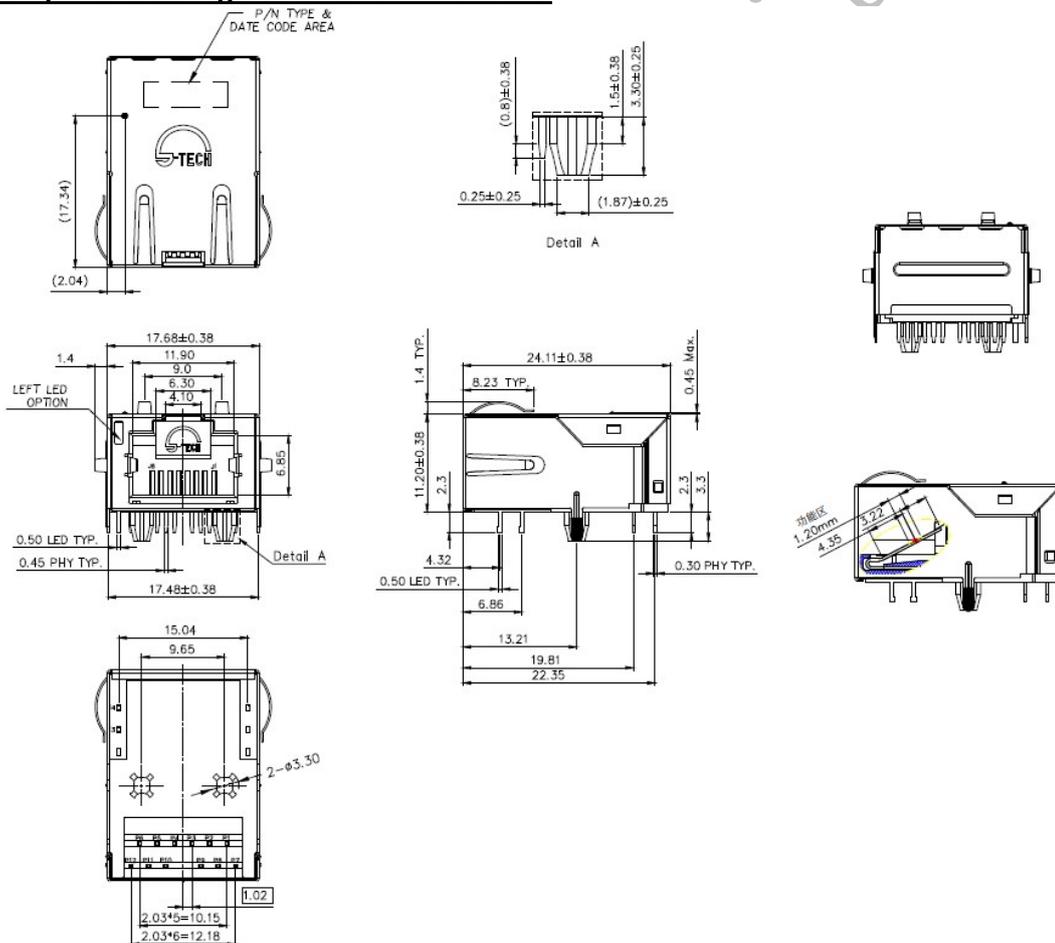
2.1 Commercial standards, specifications and report

2.1.1 MIL-STD-1344A

2.1.2 EIA-364

3 MECHANIC DIMENSIONS

Component Configuration and Dimensions

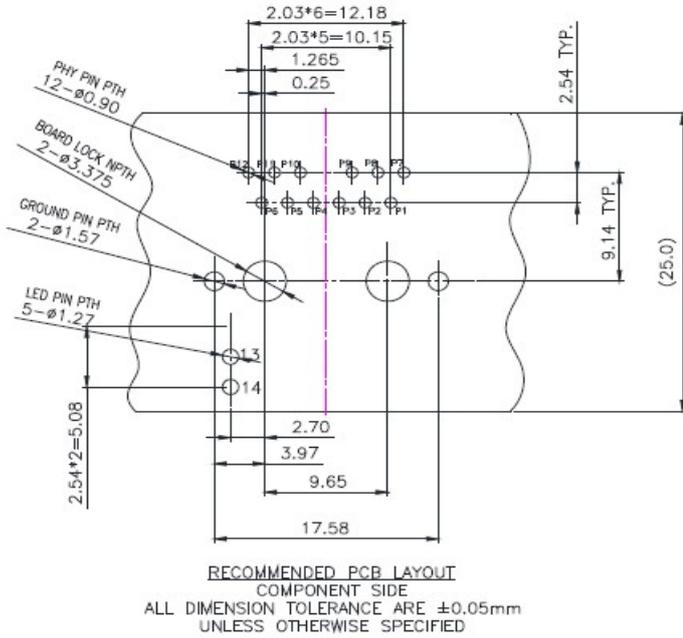


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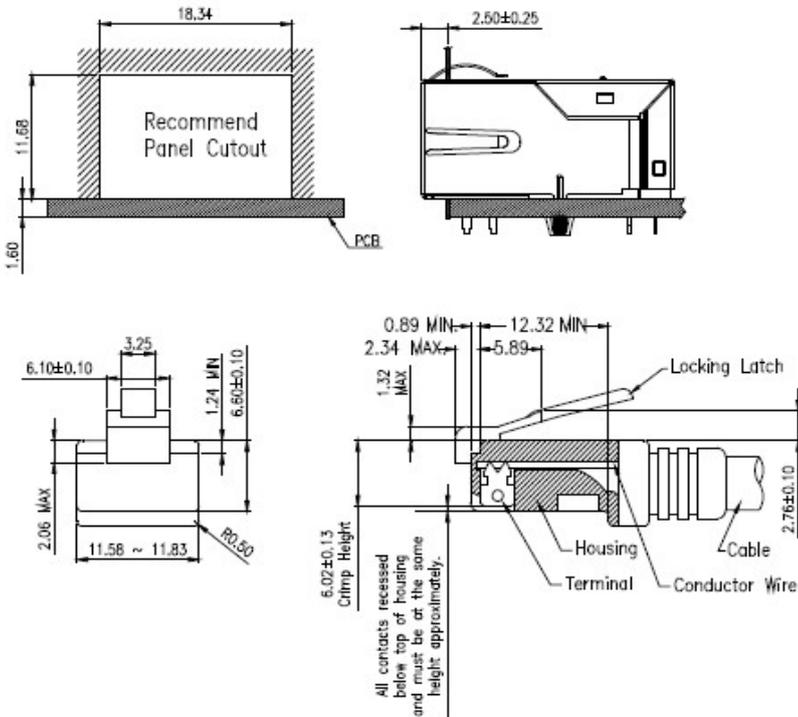
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Pins assignment for PCB Layout



Recommend Panel Cut-out and Plug Dim



All dimensions follow :
FCC subpart F, 68,500, Figure (C)(2)(i)
IEC 60603-7

STANDARD MODULAR PLUG ASSEMBLY

4 REQUIREMENTS

4.1 Design and Construction

4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.2 Materials and Finish

4.2.1 Contact :

4.2.1.1 RJ Contact : Copper alloy

Finish : (a) Contact Area : 1.25 μ m Au Min

(b) Solder tail Area : 100 μ " min. Matted Tin

(c) Underplating : 50 μ " min. Nickel over all

4.2.1.2 PHY Contact : Brass

Finish : 100 μ " Matted Tin on 50 μ " Min Nickel over all

4.2.1.3 PHY PIN Type: FLAT PIN

4.2.2 Plastic Part :

4.2.2.1 Housing : High temperature engineering plastic, Blue (285C)

Flame Class : UL94 V-0

4.2.2.2 Module & Cover: High temperature engineering plastic, Black

Flame Class : UL94 V-0

4.2.3 Shell

4.2.3.1 Shell : Stainless steel

4.2.3.2 Shell of grounding pin : pre-soldering Sn

4.3 LED Lamp

Emitting color	λ_p (nm)	$V_f@I_f=20mA$	$I_r@V_r=5V$
Green	562-568 typ565	1.7-2.6typ 2.2	10uA max

4.4 Operating and Storage Temperature

4.4.1 Operating Temperature : -40°C TO +85°C

4.4.2 Storage Temperature : -40°C TO +85°C

4.5 Mechanical Characteristics

4.5.1 Mating force : 20N MAX

4.5.2 Unmating force: 20N MAX

4.5.3 Durability : 1000 cycles

4.6 Reliability Test:

4.6.1 Resistance to soldering heat - High Temperature Resistance:
265 \pm 5/-0°C , 3-5 seconds for 2 times.

4.6.2 Rework temperature: 350°C Max. 3~5seconds for 3 times.

4.7 Environmental Test:

4.7.1 Moisture Resistance : MSL level-3

4.7.2 Saving life: 1 year

4.7.3 Thermal shock cycle Test: Expose Sample connectors under the temperature changes between -40°C and 85°C for 25 cycles holding for 30minutes at the both extremes, in accordance with test method of SPEC.

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4.7.4 Temperature life: Subject Sample connectors to temperature life at 85°C for 168 hours. EIA-364-22B, Class shell be satisfied.

4.7.5 Humidity test: Subject Sample connector, to relative humidity 85%RH and a temperature of 85°C for 168 hours. It shall be subjected to standard atmospheric.

Class shell be satisfied. MIL-STD-1344A.method:1002.2.

4.6 Performance and Test Description

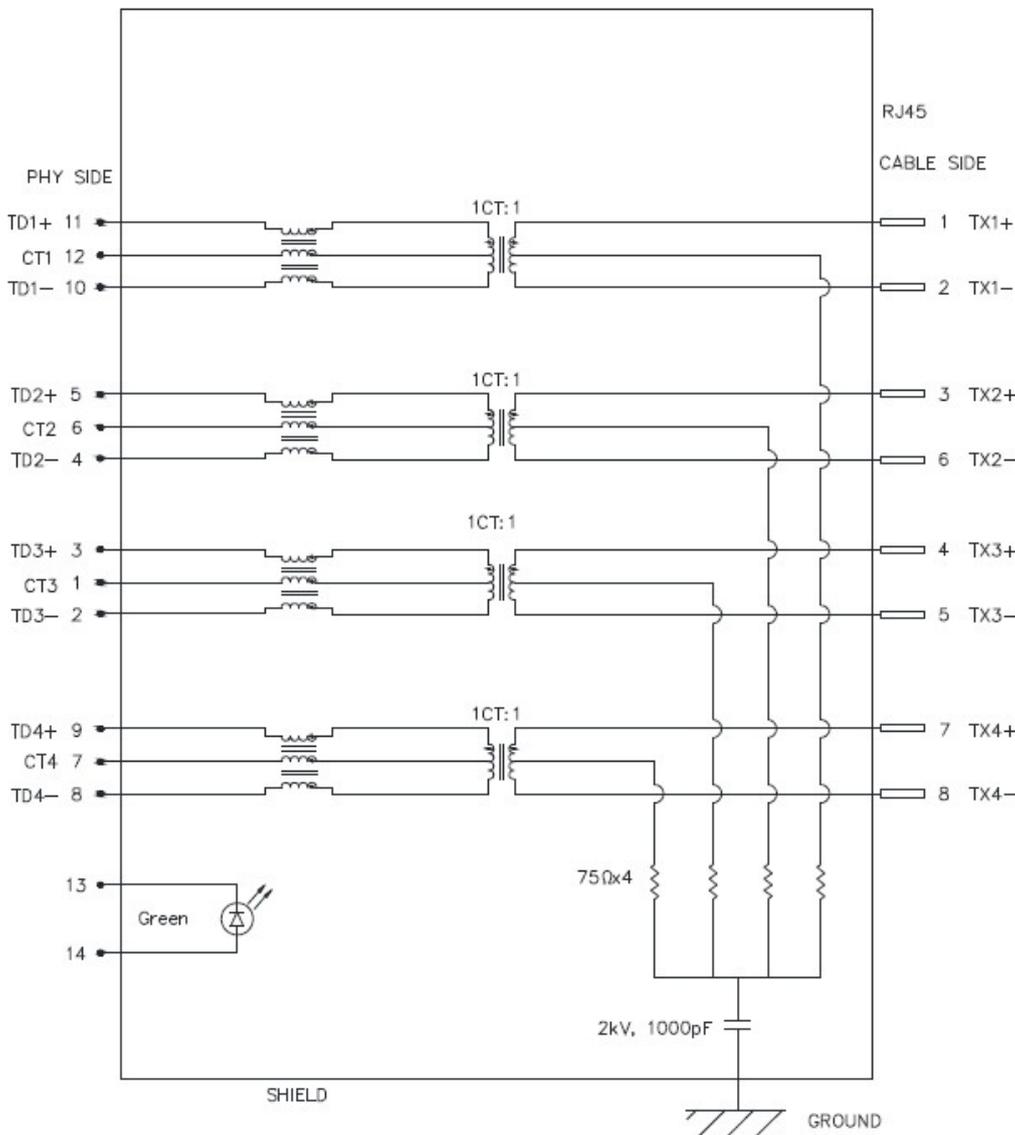
Product is designed to meet electrical, mechanical and environmental performance requirements. All tests are performed at ambient environmental conditions per

MIL-STD-1344A and EIA-364 unless otherwise specified.

4.7 Packaging and Packing All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

5. ELECTRICAL CHARACTERISTICS

5.1 Schematic



5.2 Insertion loss

- @ 1 ~50 MHz - 0.5dB MAX
- @ 50~125 MHz - 1.0dB MAX

5.3 Return loss

- @ 1~40 MHz - 20dB MIN. load 100Ω
- @ 200 MHz - 10dB MIN. load 100Ω

5.4 Cross Talk

- @ 1~125 MHz - 30dB MIN

5.5 Common Mode Rejection

- @ 1~200 MHz - 30dB MIN.

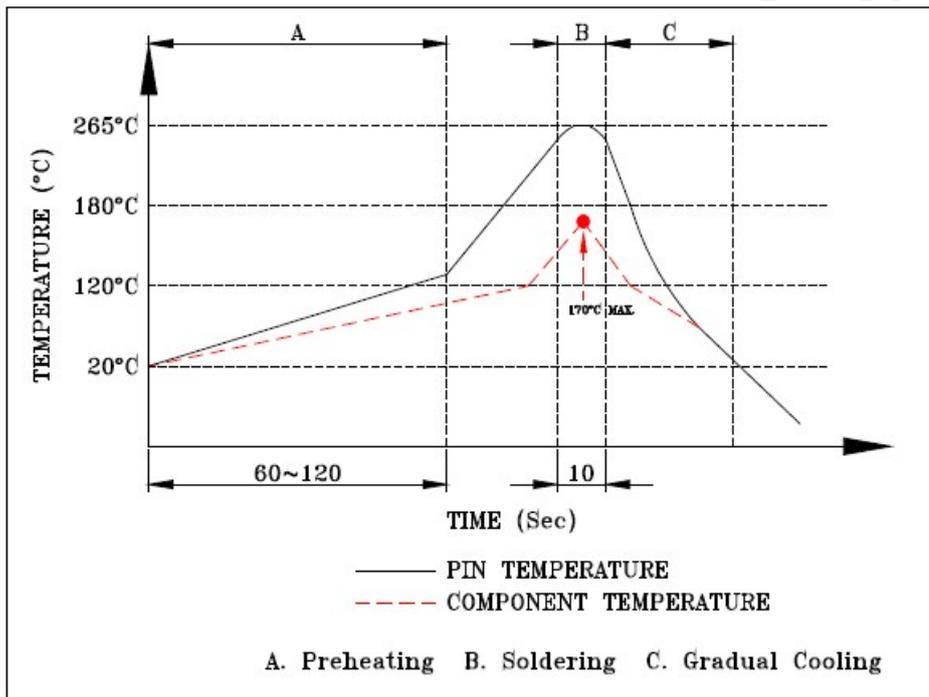
5.6 Primary Inductance

- @100KHz, 0.1V, 8mA DC BIAS
- P(11-10), P(4-5), P(3-2), P(8-9): 200 H MIN.

5.7 Hi-Pot TEST

PRIMARY TO SECONDARY: 2250 VDC

Resistance to flow solder heat



SUGGESTED WAVE SOLDER CURVE

- (1)Tip temperature : 265+5/-0°C
- (2)Tip temperature time : 3~5sec

Note: The product specification only for standard product